

Università degli Studi di Napoli FEDERICO II





PhD Vincenzo Terracciano

Innovative Approaches to Power Device Design and Semi-Physical Modeling

Tutor: <u>Andrea Irace</u> Co-Tutor: <u>Vincenzo d'Alessandro</u>

Cycle:XXXVIII

Year: First



My background

- MSc degree: *Electronic Engineering*
- Research laboratory: **OPTO-POWER LAB**
- PhD start date: 01/11/2022
- Scholarship type: ITEE
- Partner company: Vishay Semiconductor



SUMMARY OF STUDY ACTIVITIES

Ad hoc PhD courses	MSc Courses
- How to boost your PhD	-Electrodynamics of continuos media
- Academic Entreprenuership	(mathematical eingeenering)

Summer School:China-Italy Joint Laboratory on Advanced Manufacturing (CI-LAM) Summer School Chair: Giovanni Breglio



Conferences:

International Conference on Silicon Carbide and Related Materials (ICSCRM), *Sorrento Italy 2023*.

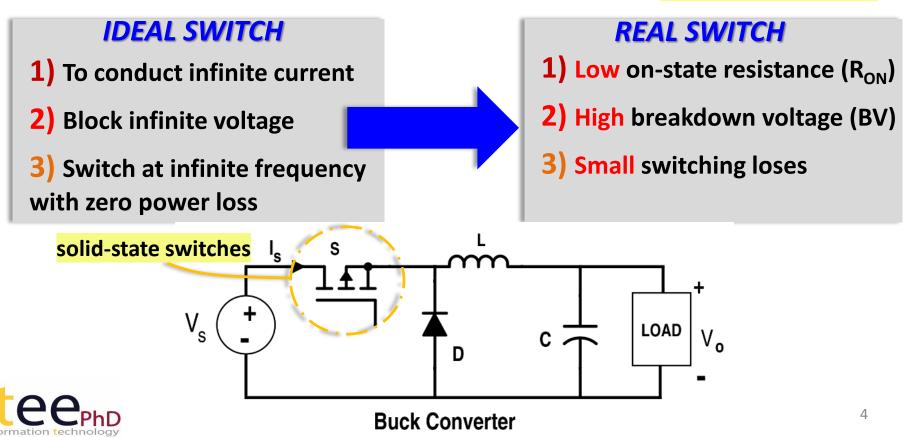


29th International Workshop on Thermal Investigations of ICs and Systems (THERMINIC), Budapest Ungary 2023.



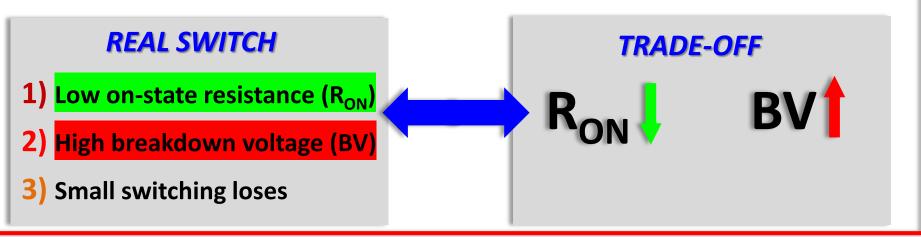
POWER SEMICONDUCTOR PHYSICS

- <u>Power Semiconductor Physics</u> is concerned with the study of the physical principles and properties of semiconductors used in power electronic devices, such as wide-bandgap semiconductor devices.
- These power devices are crucial for electrical energy conversion and include components like diodes, transistors, and rectifiers.
- In power electronics systems, power devices are used as solid-state switches.



RESEARCH ACTIVITY¹

RESEARCH ACTIVITY PROBLEM



APPROACHES TO IMPROVE THIS TRADE-OFF

- 1) Employ semiconductors with superior properties for power switching, such as wide-bandgap (WBG) materials
- 2) Involves innovation in device architecture

PAPER

"SiC GAA MOSFET Concept for High Power Electronics Performance Evaluation through Advanced TCAD Simulations"



RESEARCH ACTIVITY²

RESEARCH ACTIVITY PROBLEM

To realize a **compact model** in the form of a **SPICE-compatible subcircuit** describing the **electrical and electrothermal behavior** of a particular SiC diode: **Merged PiN Schottky** (MPS). In addition, the model has to take into account of the detrimental snapback mechanism, which can lead, where we have multiple cells in parallel, to current-focusing. Through a compact model, it would be possible to reduce both the time and complexity of a TCAD simulation, as in the case of **TCAD electrothermal simulations**.

APPROACHES TO REALIZE THESE MODELS

The approach is based on a **comparison** of Sentaurus TCAD simulations and the SPICE simulations, while specifically for electrothermal analysis we exploited the thermal equivalent of Ohm's law (TEOL)

PAPERS

"A Geometry-Scalable Physically-Based SPICE Compact Model for SiC MPS Diodes Including the Snapback Mechanism"

"A Simple Electrothermal Compact Model for SiC MPS Diodes Including the Snapback Mechanism"



Products

[P1]	SiC GAA MOSFET Concept for High Power Electronics Performance Evaluation through Advanced TCAD Simulations
<mark>[P2]</mark>	A Geometry-Scalable Physically-Based SPICE Compact Model for SiC MPS Diodes Including the Snapback Mechanism
<mark>[P3]</mark>	A Simple Electrothermal Compact Model for SiC MPS Diodes Including the Snapback Mechanism



Thank You For Your Attention

